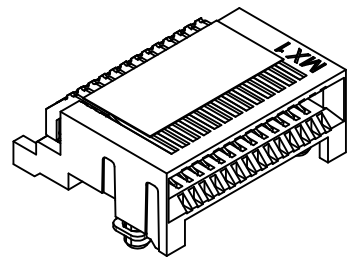
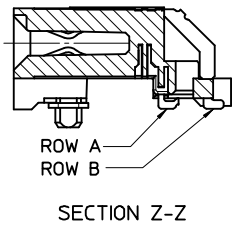
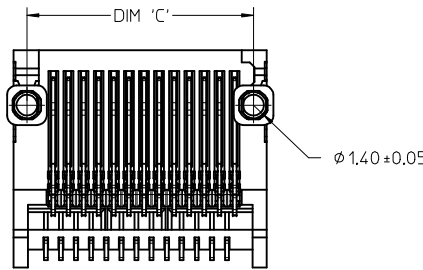
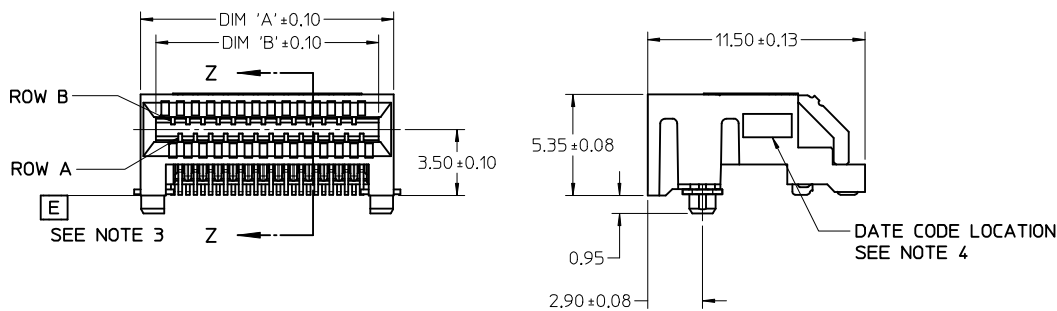
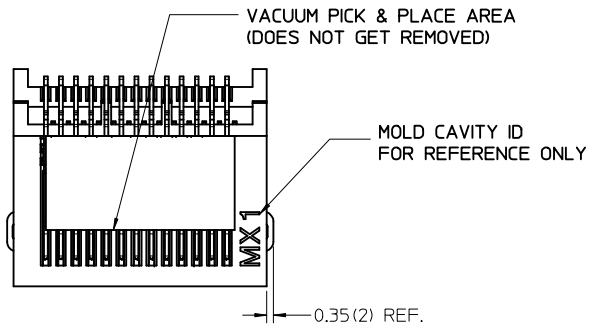


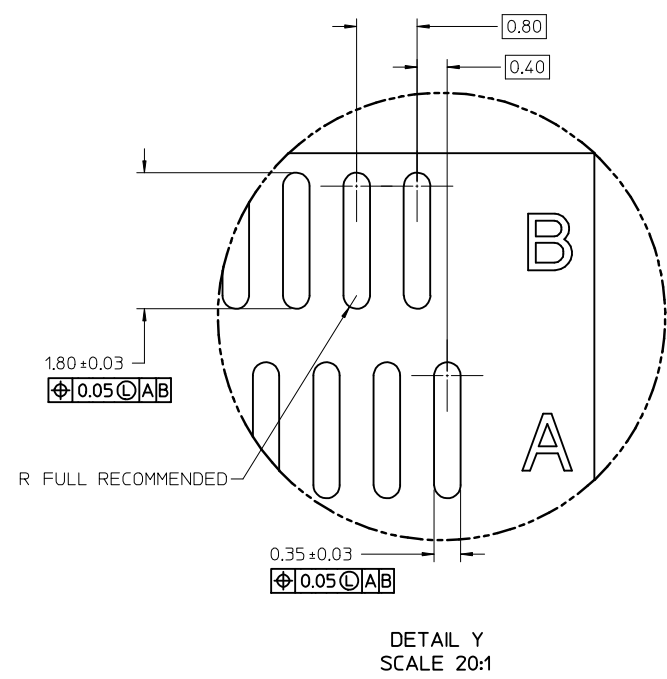
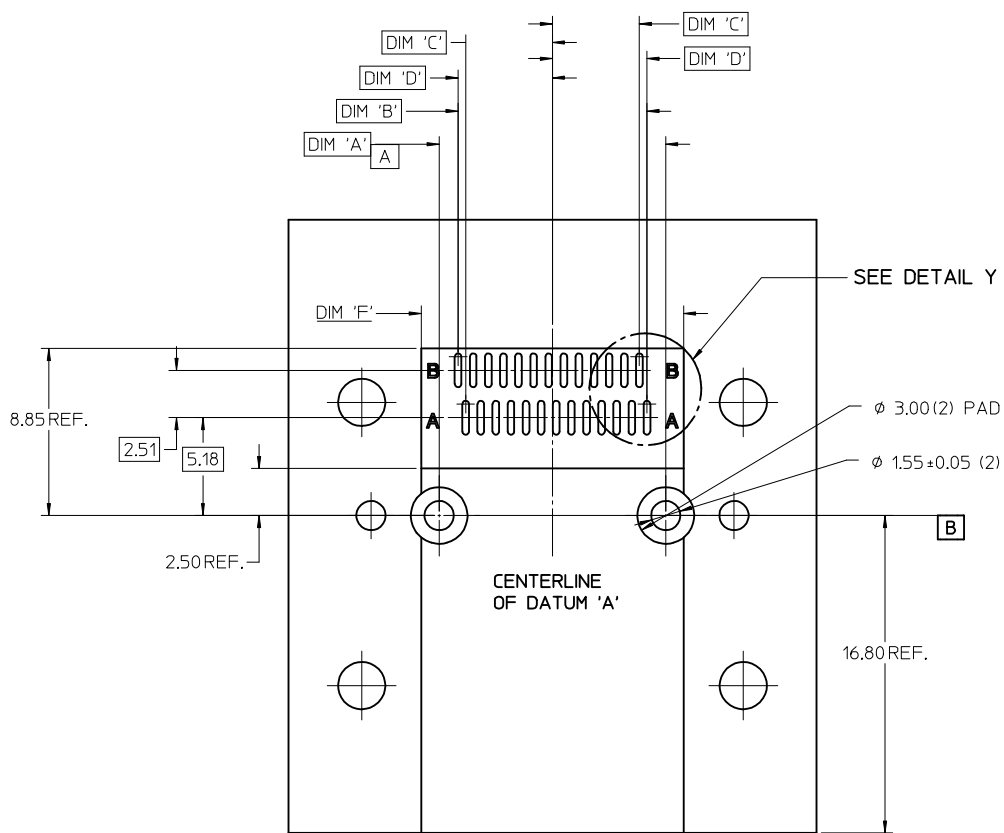
CIRCUIT SIZE	ITEM NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
26	75586-0101	OPTION 1	13.40	11.80	12.00
26	75586-0102	OPTION 2	13.40	11.80	12.00
38	75586-0103	OPTION 1	18.20	16.60	16.80
38	75586-0104	OPTION 2	18.20	16.60	16.80
68	75586-0105	OPTION 1	30.20	28.60	28.80
68	75586-0106	OPTION 2	30.20	28.60	28.80



- NOTES
- MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0, BLACK
TERMINALS - COPPER ALLOY
 - PLATING:
OPTION 1
CONTACT AREA - 0.38 μm MIN GOLD OVER 2.54 μm MIN NICKEL
SOLDER FOOT AREA - 2.54 - 5.09 μm TIN OVER 1.27 μm MIN NICKEL.
OPTION 2
CONTACT AREA - 0.76 μm MIN GOLD OVER 2.54 μm NICKEL
SOLDER AREA - 2.54 - 5.09 μm TIN OVER 1.27 μm MIN NICKEL.
 - TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/004 MEASURED FROM FRONT HOUSING STAND OFF (DATUM E)
 - DATE CODE: 4 DIGIT (3 DIGIT DATE, 1 DIGIT YEAR)
 - CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1
 - TO BE USED WITH EXTERNAL CABLES (74546 & 74547 SERIES) AND GUIDE FRAMES (74540 & 74548 SERIES)
 - TESTER/ANALYZER CABLES AVAILABLE (74557 & 74558 SERIES)
 - PACKAGED PER PACKAGING SPECIFICATION: PK-75586-002
 - CONFORMS TO PRODUCT SPECIFICATION: PS-75586-001
 - THIS PART CONFORMS TO CLASS C REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

REV NOTE 2 IEC NO: UCP2015-0453 DRW:KINGHAM 2014/07/31 CHKD:MCLELLAND 2014/08/01 APPR:MCLELL 2014/08/01	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY KLANG	DATE 12/06/2006	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex			
		4 PLACES ± ---	± ---	± ---	CHECKED BY JSWENSON	DATE 12/06/2006				
		3 PLACES ± ---	± ---	± ---	APPROVED BY MBANAKIS	DATE 12/06/2006	DOCUMENT NO. SD-75586-005			
2 PLACES ± 0.13	± ---	± ---	MATERIAL NO.		SHEET NO. 1 OF 6					
1 PLACE ± 0.25	± ---	± ---	ANGULAR ±1/2°		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
0 PLACE ±	±	±	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

MOTHERBOARD FOOTPRINT RECOMMENDATION

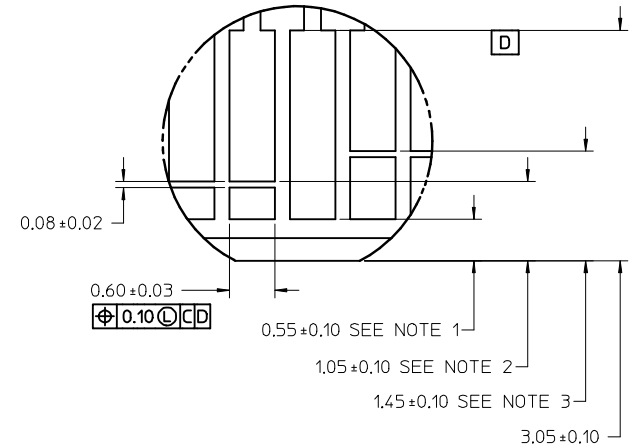
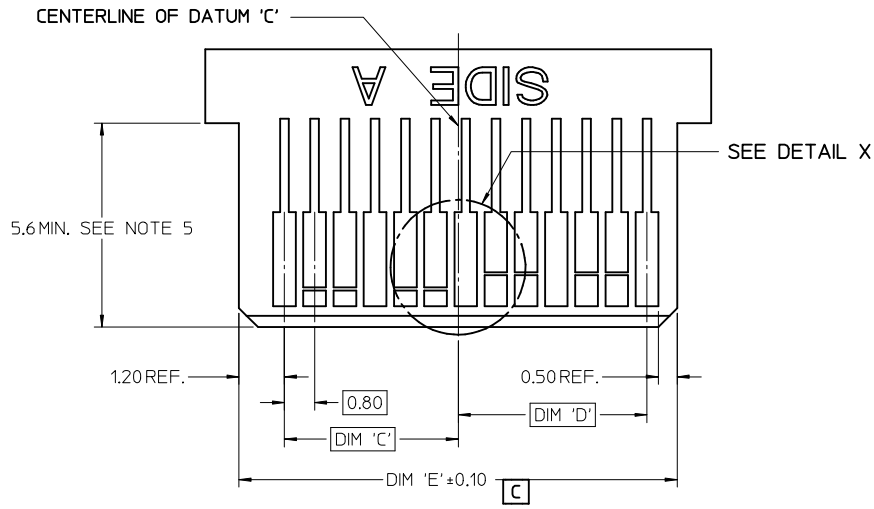


NOTES:
 1. SEE 74540 OR 74548 SERIES FOR GUIDE FRAME FOOT PRINT AND KEEP OUT AREA.

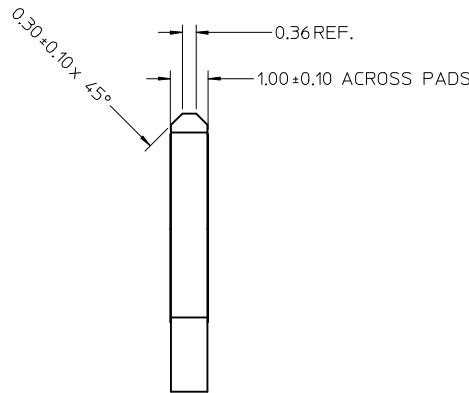
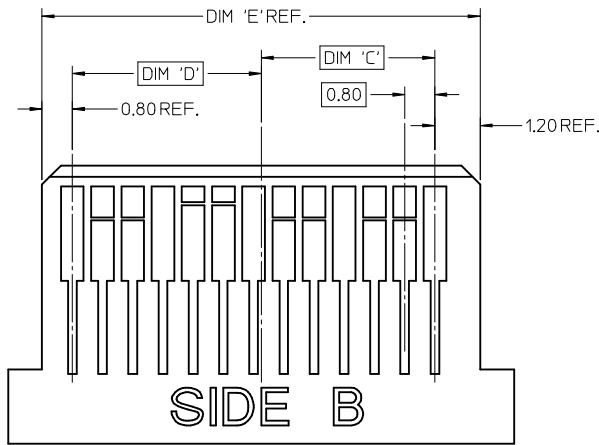
CIRCUIT SIZE	TERM/SIDE 'N'	DIMENSIONS					
		PAG TO PEG	FIRST PAD TO LAST PAD	CENTERLINE TO PAD	CENTERLINE TO PAD	MODULE BOARD WIDTH	CONNECTOR WIDTH
		DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'
26	13	12.00	10.00	4.60	5.00	11.60	13.90
38	19	16.80	14.80	7.00	7.40	16.40	18.70
68	34	28.80	26.80	13.00	13.40	28.40	30.70

SEE SHEET 1 EC NO: UCP2015-0453 DRWING: INGRAM 2014/07/31 CHKD: MCCLELLAND 2014/08/01 APPR: MCCLELL 2014/08/01	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		mm	INCH	MM ONLY	10:1	METRIC		
		4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE	
		3 PLACES	± ---	± ---	KLANG	12/06/2006	IPASS R/A CONNECTOR EXTERNAL ASSEMBLY	
	2 PLACES	± 0.13	± ---	CHECKED BY	DATE	SOLDER RING		
	1 PLACE	± 0.25	± ---	JSWENSON	12/06/2006	molex		
	0 PLACE	±	±	APPROVED BY	DATE	DOCUMENT NO.		
		ANGULAR ±1/2°		MBANAKIS	12/06/2006	SD-75586-005		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SHEET NO. 2 OF 6		
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

MODULE BOARD FOOTPRINT RECOMMENDATION



DETAIL X
SCALE 20:1



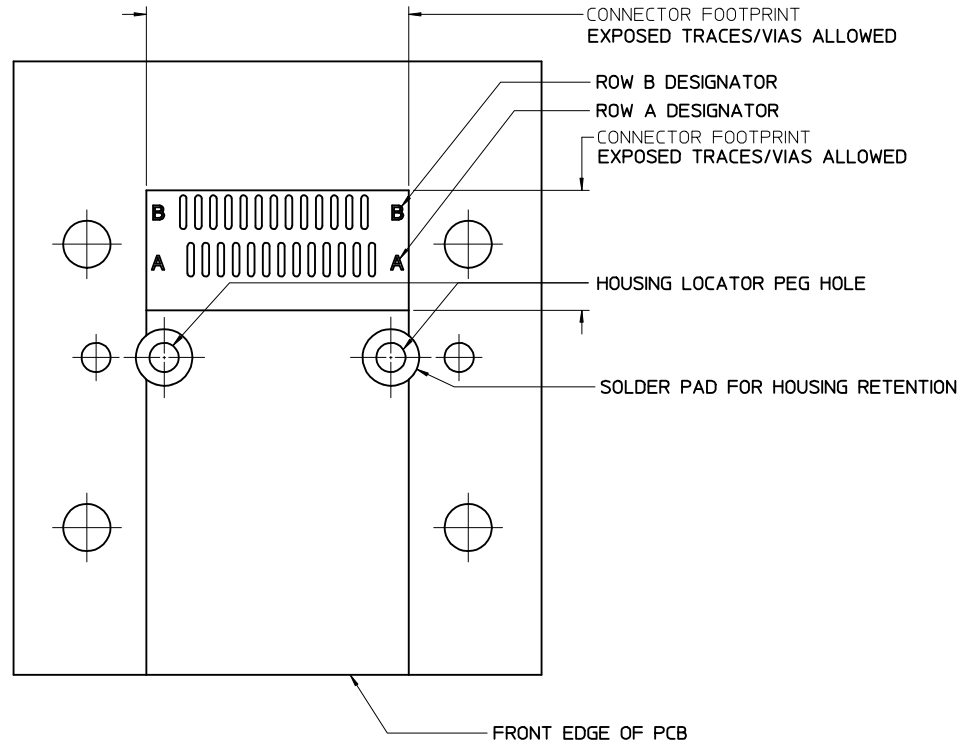
NOTES:

1. PAD CONFIGURATION FOR FIRST MATE.
2. PAD CONFIGURATION FOR SECOND MATE.
3. PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS).
4. FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION.
5. MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TONGUE.

CIRCUIT SIZE	TERM/SIDE 'N'	MODULE BOARD WIDTH		
		CENTERLINE TO PAD	CENTERLINE TO PAD	MODULE BOARD WIDTH
		DIM 'C'	DIM 'D'	DIM 'E'
26	13	4.60	5.00	11.60
38	19	7.00	7.40	16.40
68	34	13.00	13.40	28.40

SEE SHEET 1 EC NO: UCP2015-0453 DRAWN BY: DRWINGBINGHAM 2014/07/31 CHKD: TMCLELLAND 2014/08/01 APPR: TMCLELL 2014/08/01	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			mm	INCH	DRAWN BY KLANG	DATE 12/06/2006	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING	
		4 PLACES ± ---	± ---	± ---	CHECKED BY JSWENSON	DATE 12/06/2006	molex	
		3 PLACES ± ---	± ---	± ---	APPROVED BY MBANAK I S	DATE 12/06/2006		
2 PLACES ± 0.13	± ---	± ---	ANGULAR ± 1/2°		MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
1 PLACE ± 0.25	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART	SD-75586-005	3 OF 6	
0 PLACE ±	±	±	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

CONNECTOR FOOTPRINT ZONE IDENTIFICATION



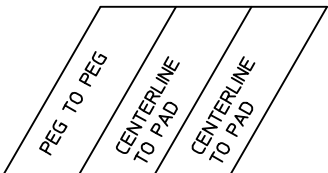
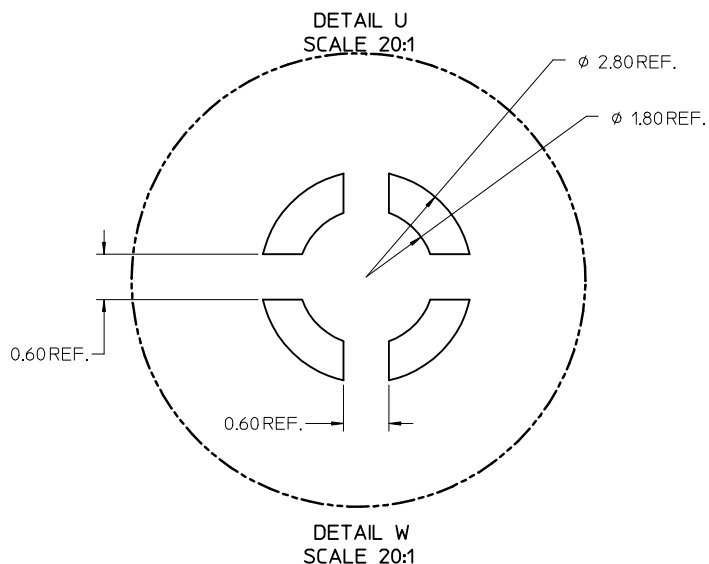
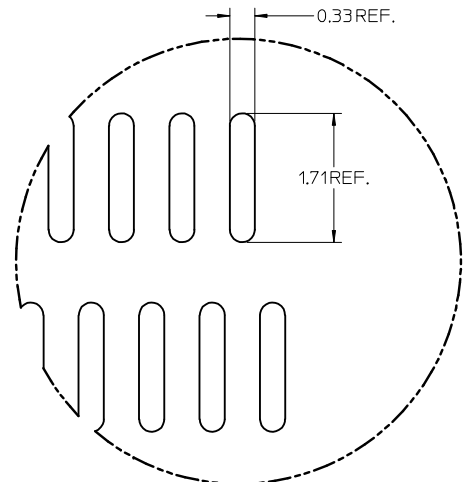
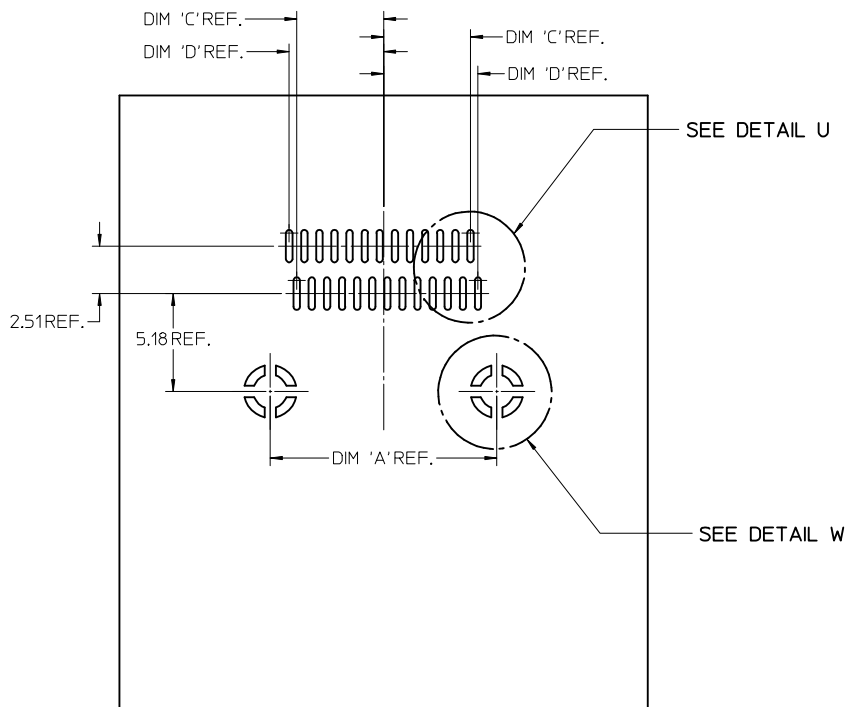
SEE SHEET 1 EC NO: UCP2015-0453 DRAWN BY: DRWINKBINGHAM 2014/07/31 CHKD: TMCLELLAND 2014/08/01 APPR: TMCLELL 2014/08/01	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				DRAWN BY KLANG	DATE 12/06/2006	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex DOCUMENT NO. SD-75586-005 SHEET NO. 4 OF 6		
		4 PLACES ± ---	± ---	CHECKED BY JSWENSON	DATE 12/06/2006			
		3 PLACES ± ---	± ---	APPROVED BY MBANAK I S	DATE 12/06/2006			
2 PLACES ± 0.13	± ---	MATERIAL NO.						
1 PLACE ± 0.25	± ---	ANGULAR ±1/2°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
0 PLACE ±	±	SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

NOTES:

1. STENCIL RECOMMENDATION IS A GUIDELINE ONLY.
2. MANUFACTURING PROCESS PARAMETERS WILL DEFINE THE ACTUAL STENCIL DEFINITION.
3. RECOMMENDED STENCIL THICKNESS IS 0.13MM.

SOLDER STENCIL RECOMMENDATION

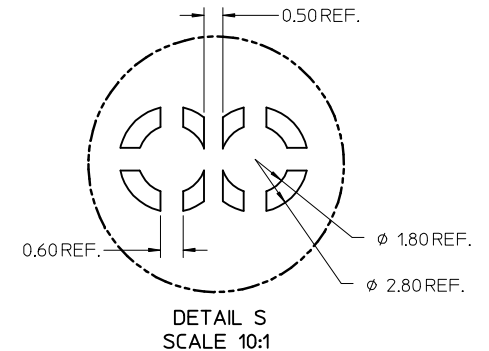
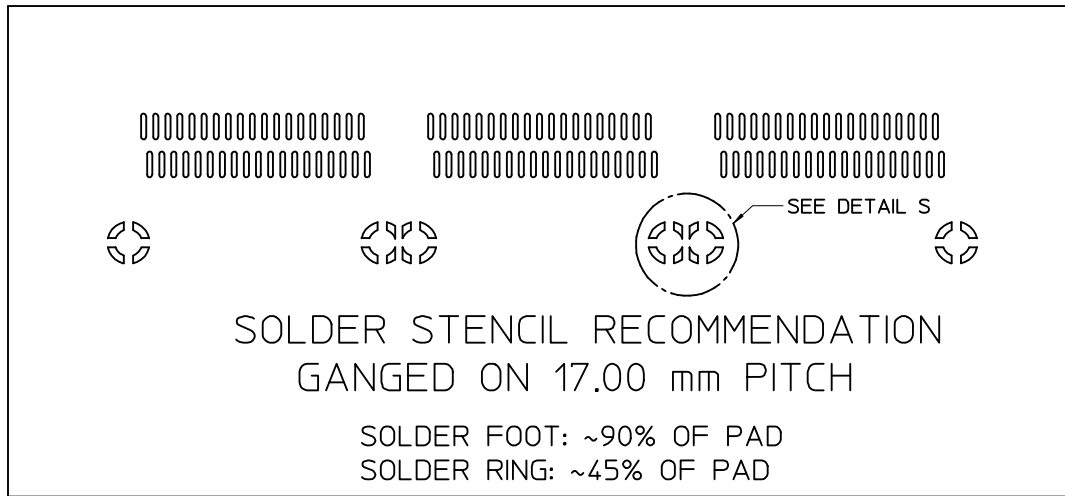
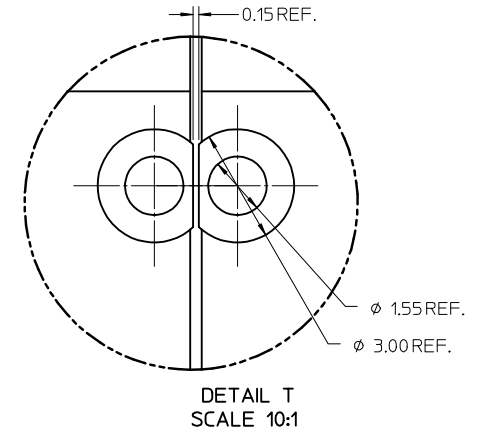
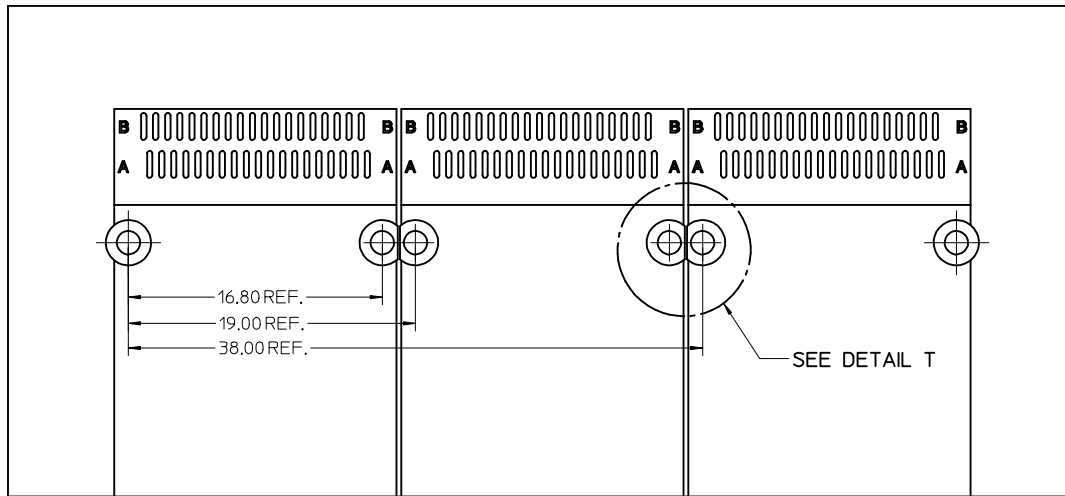
SOLDER FOOT: ~90% OF PAD
 SOLDER RING: ~45% OF PAD



CIRCUIT SIZE	TERM/SIDE 'N'	DIM 'A'	DIM 'C'	DIM 'D'
26	13	12.00	4.60	5.00
38	19	16.80	7.00	7.40
68	34	26.80	13.00	13.40

SEE SHEET 1 EC NO: UCP2015-0453 DRAWN BY: DRWINGBINGHAM 2014/07/31 CHKD: MCLELLAND 2014/08/01 APPR: MCLELL 2014/08/01 C2	QUALITY SYMBOLS $\nabla = 0$ $\nabla = 0$ $\nabla = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>\pm ---</td> <td>\pm ---</td> </tr> <tr> <td>3 PLACES</td> <td>\pm ---</td> <td>\pm ---</td> </tr> <tr> <td>2 PLACES</td> <td>\pm 0.13</td> <td>\pm ---</td> </tr> <tr> <td>1 PLACE</td> <td>\pm 0.25</td> <td>\pm ---</td> </tr> <tr> <td>0 PLACE</td> <td>\pm</td> <td>\pm</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	\pm ---	\pm ---	3 PLACES	\pm ---	\pm ---	2 PLACES	\pm 0.13	\pm ---	1 PLACE	\pm 0.25	\pm ---	0 PLACE	\pm	\pm	DIMENSION STYLE MM ONLY DRAWN BY: KLANG DATE: 12/06/2006 CHECKED BY: JSWENSON DATE: 12/06/2006 APPROVED BY: MBANAK I S DATE: 12/06/2006	SCALE 5:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex
		mm	INCH																				
	4 PLACES	\pm ---	\pm ---																				
	3 PLACES	\pm ---	\pm ---																				
2 PLACES	\pm 0.13	\pm ---																					
1 PLACE	\pm 0.25	\pm ---																					
0 PLACE	\pm	\pm																					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR $\pm 1/2^\circ$	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-75586-005	SHEET NO. 5 OF 6																		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																							

38 CIRCUIT GANGED ON 19.00 mm CENTERLINE



NOTES:

1. STENCIL RECOMMENDATION IS A GUIDELINE ONLY.
2. MANUFACTURING PROCESS PARAMETERS WILL DEFINE THE ACTUAL STENCIL DEFINITION.
3. RECOMMENDED STENCIL THICKNESS IS 0.13MM.

SEE SHEET 1 EC NO: UCP2015-0453 DRAWN BY: DRINKBINGHAM 2014/07/31 CHKD: MCCLELLAND 2014/08/01 APPR: MCCLELL 2014/08/01	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY KLANG	DATE 12/06/2006	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING			
4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.13 ± ---	1 PLACE ± 0.25 ± ---	CHECKED BY JSWENSON	DATE 12/06/2006	DOCUMENT NO. SD-75586-005 SHEET NO. 6 OF 6			
0 PLACE ± ±	ANGULAR ±1/2°		APPROVED BY MBANAK I S		DATE 12/06/2006				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
C2	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART					